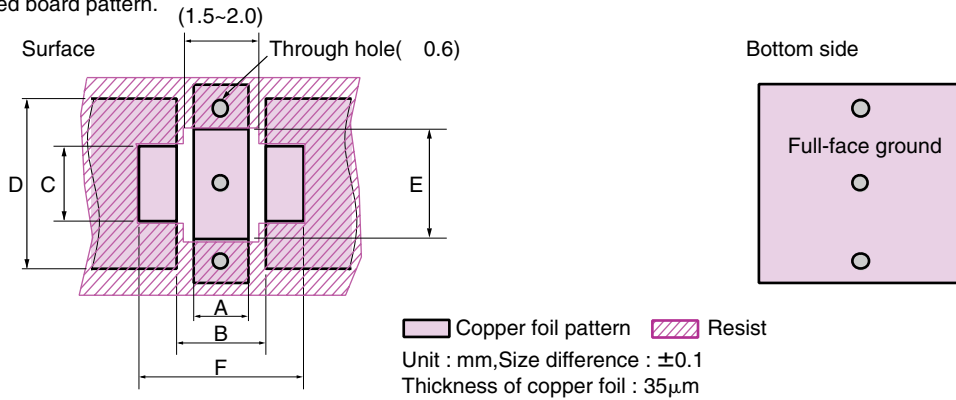


# HANDLING PRECAUTIONS

## ■Soldering (Exclusively for reflow soldering. Not applicable to flow soldering.)

### 1. Basic design

Recommended board pattern.



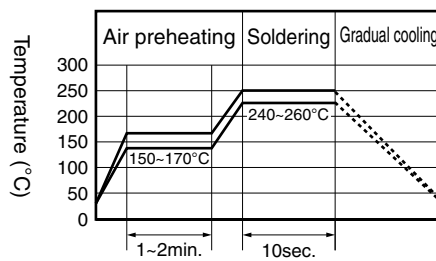
Type	A	B	C	D	E	F
CTH20 type	0.8	1.5	1.2	2.5	1.8	3.2
CTH30 type	1.5	2.5	2.2	4.0	3.2	4.8
CTH32 type	1.5	2.5	3.0	6.0	5.0	4.8

\*The D dimension presupposes the rated current.

### 2. General cautions for soldering

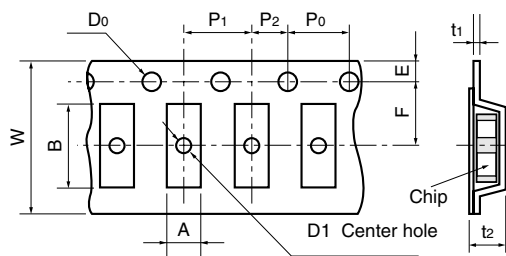
- (1) High soldering temperature and long soldering time can cause leaching of the termination, decrease in adhesion strength, and a drop in capacitance value, etc.
- (2) For soldering, please refer to the soldering curves below.

Reflow soldering temperature patterns(lead-free solder)



## ■Taping

### Taping Specifications



Type	A	B	W	F	E	P1	P2	P0	D0	D1	t1	t2	Hole
CTH20	1.45 $\pm$ 0.2	2.3 $\pm$ 0.2	8.0 $\pm$ 0.2	3.50 $\pm$ 0.05	1.75 $\pm$ 0.1	4.0 $\pm$ 0.1	2.00 $\pm$ 0.05	4.0 $\pm$ 0.1	1.5 +0.1 -0	1.15 $\pm$ 0.05	0.6 under	3.0 under	Square embossed hole
CTH30	2.0 $\pm$ 0.2	3.6 $\pm$ 0.2											
CTH32	2.9 $\pm$ 0.2	3.6 $\pm$ 0.2											

## ■Package Qty.

Type	Taping Qty.	Bulk Qty.
CTH20	2,000pcs / reel	1,000pcs / bag
CTH30	2,000pcs / reel	1,000pcs / bag
CTH32	1,000pcs / reel	1,000pcs / bag